# LabAdviser update: 16/12 2019

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| Updated Subject  | Contributor | Link to the updated pages |
| **InP etch – III-V ICP** Comparing HBr and Cl2 chemistry on nanostructuresInP etching with Cl2 and H2 (+Ar) | **Aurimas Sakanas @Fotonik****Berit Herstrøm @Nanolab** | [/Etch/III-V\_ICP/InP-InGaAsP-InGaAs#InP\_etch\_with\_HBr\_chemistry\_.282019.29](http://labadviser.nanolab.dtu.dk/index.php/Specific_Process_Knowledge/Etch/III-V_ICP/InP-InGaAsP-InGaAs#InP_etch_with_HBr_chemistry_.282019.29)See under other tests[/III-V\_ICP/InP-InGaAsP-InGaAs#InP\_etch\_with\_Cl2.2FH2\_and\_a\_Si\_carrier\_wafer\_.282019.29](http://labadviser.nanolab.dtu.dk/index.php/Specific_Process_Knowledge/Etch/III-V_ICP/InP-InGaAsP-InGaAs#InP_etch_with_Cl2.2FH2_and_a_Si_carrier_wafer_.282019.29)And[Etch/III-V\_ICP/InP-InGaAsP-InGaAs/InP\_etch\_with\_Cl2-H2-Ar](http://labadviser.nanolab.dtu.dk/index.php/Specific_Process_Knowledge/Etch/III-V_ICP/InP-InGaAsP-InGaAs/InP_etch_with_Cl2-H2-Ar) |
| **RCA cleaning and storage of wafers for the furnaces** | **Pernille V. Larsen @Nanolab** | [Thermal\_Process/Storage\_and\_cleaning\_of\_wafer\_to\_the\_A,\_B,\_C\_and\_E\_stack\_furnaces](http://labadviser.nanolab.dtu.dk/index.php/Specific_Process_Knowledge/Thermal_Process/Storage_and_cleaning_of_wafer_to_the_A%2C_B%2C_C_and_E_stack_furnaces) |

# Equipment Manuals updated in LabManager (since 26th of October):

As an approved user on a piece of equipment you have to make sure you have read and understood the latest version of the manual before using the equipment.

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|  | **5. 3.00.01) Generic Manual for Less Complicated Equipment**, ver 3 |
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|  | **5. 3. 7.49) Manual for Lifetime scanner MDPmap**, ver 3 |
|  |  |
|  | **5. 3. 5.16) Manual for Furnace: Multipurpose Annealing**, ver 2.5 |
|  | **3. 1. 1.16) APV Developer: TMAH Manual**, ver 3.1 |
|  | **5. 3. 4.01) Manual for RCA clean**, ver 7 |